

Amendment

TOWNSEND and TOWNSEND and CREW, LLP
(415) 576-0200

Corres. and Mail

Attorney Docket No. A1126/T08910

PTC Ref No. 016301-008910US

AF/1763

DEC 20 2000

BOX AF

In re application of: KRAMADHAKTI V. RAVI et al.

Application No.: 09/362,504

Filed: July 27, 1999

Group Art Unit: 1763

For: METHOD FOR REDUCING THE INTRINSIC STRESS
OF HIGH DENSITY PLASMA FILMS

THE ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

Date: December 15, 2000

I hereby certify that this is being deposited with the United States
Postal Service as first class mail in an envelope addressed to:

Assistant Commissioner for Patents
Washington, D.C. 20231

Signed: Andrea

**RESPONSE TO OFFICE ACTION UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE-EXAMINING GROUP 1763**

Sir:

Transmitted herewith is an amendment in the above-identified application.

If any extension of time is needed, then this response should be considered a petition therefor.
The filing fee has been calculated as shown below:

(Col. 1)	(Col. 2)	(Col. 3)
CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA
TOTAL * 21	MINUS ** 21	= 0
INDEP. * 5		
MINUS *** 5		
[] FIRST PRESENTATION OF MULTIPLE DEP. CLAIM		

SMALL ENTITY		OTHER THAN SMALL ENTITY	
RATE	ADDIT. FEE	RATE	ADDIT. FEE
x \$9.00 =		x \$18.00 =	\$0.00
x \$40.00 =		x \$80.00 =	\$0.00
+ \$135.00 =		+ \$270.00 =	
TOTAL ADDIT. FEE		TOTAL	\$0.00

[X] No fee is due.

Please charge Deposit Account No. 20-1430 as follows:

[] Claims fee \$ _____
[X] Any additional fees associated with this paper or during the pendency of this application

NO extra copies of this sheet are enclosed.

PLEASE ADDRESS ALL CORRESPONDENCE TO:

PATENT COUNSEL

APPLIED MATERIALS, INC.

P.O. BOX 450A

SANTA CLARA, CA 95052

Telephone: (415) 576-0200
Fax: (415) 576-0300

PA 3116632 v1

TOWNSEND and TOWNSEND and CREW LLP

Chun-Pok Leung
Reg. No. 41,405
Attorneys for Applicant

RECEIVED
TELELOGY CENTER 1700
12/15/2000

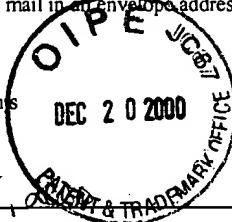
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:

Box AF
Assistant Commissioner for Patents
Washington, D.C. 20231

On December 15

TOWNSEND and TOWNSEND and CREW LLP

By: Andrea



**RESPONSE TO OFFICE ACTION
UNDER 37 CFR 1.116 EXPEDITED
PROCEDURE - EXAMINING GROUP
1763**

PATENT

Attorney Docket No.: A1126/T08910
TTC Reference No.: 16301-008910

#14 E/M
12/26/00
MN

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

KRAMADHATI V. RAVI et al.

Application No.: 09/362,504

Filed: July 27, 1999

For: METHOD FOR REDUCING THE
INTRINSIC STRESS OF HIGH
DENSITY PLASMA FILMS

Examiner: Rudy Zervigon

**RESPONSE TO OFFICE ACTION UNDER
37 CFR 1.116 EXPEDITED PROCEDURE
EXAMINING GROUP 1763**

TECHNOLOGY CENTER 1700
12/22/00

RECEIVED
U.S. PATENT AND TRADEMARK OFFICE

Box AF

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Final Office Action mailed October 27, 2000, please
reconsider this application in view of the following comments.

IN THE CLAIMS:

The claims are unamended, but are reproduced below for the Examiner's convenience and reference.

16. An integrated circuit formed on a semiconductor substrate by the method of:

- flowing a process gas into a substrate processing chamber;